

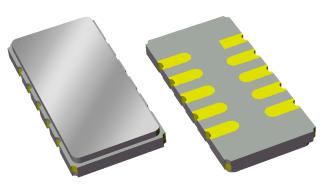
Features

- For broadband applications
- Typical 3 dB bandwidth of 10 MHz
- High attenuation
- No impedance matching required for operation at 50 Ω
- Single-ended operation
- Ceramic Surface Mount Package (SMP)
- Replaces Sawtek P/N 851921 (BW 3dB=10 MHz)

Package

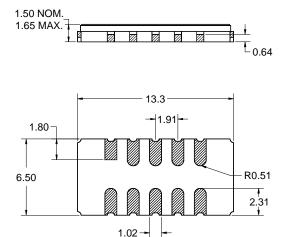
Surface Mount 13.3 x 6.50 x 1.50 mm SMP-53C

- Hermetic
- RoHS compliant (2002/95/EC), Pb-free (pb)



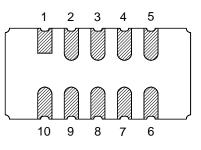
Pin Configuration

Bottom View



Dimensions shown are nominal in millimeters All tolerances are ± 0.15 mm except overall length and width ± 0.10 mm

Body: *Al*₂O₃ ceramic Lid: *Kovar*, *Ni* plated Terminations: *Au* plating 0.5 - 1.0μm, over a 2 - 6μm *Ni* plating



Single-ended Configuration

Pin No.	Description			
10	RF Input			
5	RF Output			
1,6	Ground			
2,3,4	Case Ground			
7,8,9	Case Ground			



Electrical Specifications ⁽¹⁾

Operating Temperature Range: (2) -30

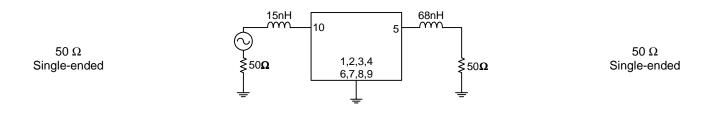
-30 to +85 °C

Parameter ⁽³⁾	Minimum	Typical ⁽⁴⁾	Maximum	Unit
Center Frequency	-	140	-	MHz
Minimum Insertion Loss	-	20.87	21.7	dB
Lower 1 dB Bandedge ⁽⁵⁾	-	135.38	135.524	MHz
Upper 1 dB Bandedge	144.508	144.79	-	MHz
Lower 3 dB Bandedge ⁽⁵⁾	-	135.00	135	MHz
Upper 3 dB Bandedge	145	145.24	-	MHz
Lower 40 dB Bandedge ⁽⁵⁾	133.379	133.85	-	MHz
Upper 40 dB Bandedge	-	146.72	146.551	MHz
Amplitude Variation				
135.524 - 144.508 MHz	-	0.7	0.94	dB
Phase Linearity				
135.524 - 144.508 MHz	-	5	6.31	deg
Group Delay Variation				
135.524 - 144.508 MHz	-	45	57.3	nsec
Absolute Delay	-	1.52	-	μsec
Relative Attenuation ⁽⁵⁾				
15 - 130 MHz	47.8	50	-	dB
130 - 133 MHz	52	57	-	dB
147 - 150 MHz	50.6	53	-	dB
150 - 350 MHz	51.3	53	-	dB
Source Impedance ⁽⁶⁾	-	50	-	Ω
Load Impedance ⁽⁶⁾	-	50	-	Ω
Substrate Material	-	LINbO ₃	-	-
Temperature Coefficient of Frequency	-	-94	-	ppm/°C

Notes:

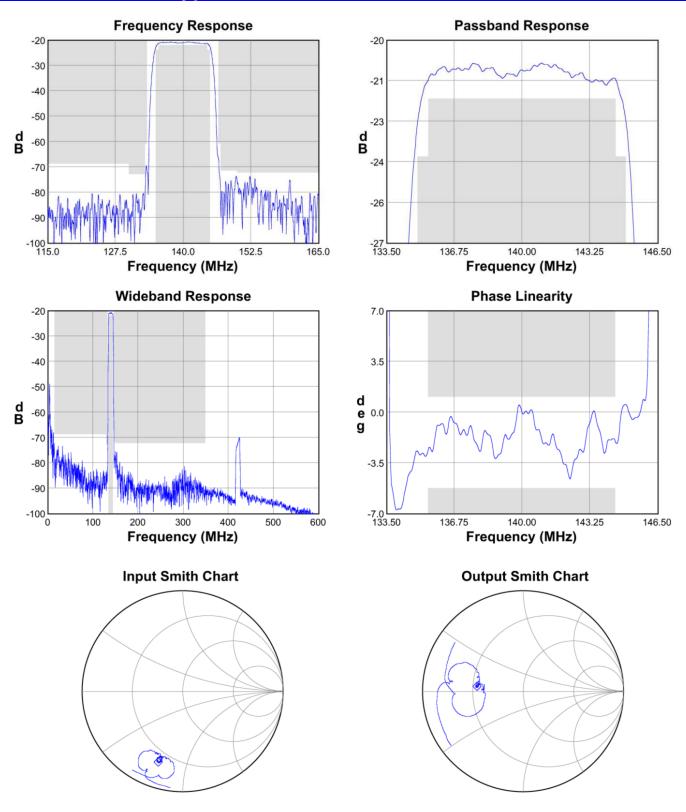
- 1. All specifications are based on the TriQuint test circuit shown below
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 4. Typical values are based on average measurements at room temperature
- 5. All attenuation measurements are measured relative to minimum insertion loss
- 6. This is the optimum impedance in order to achieve the performance shown

Test Circuit:



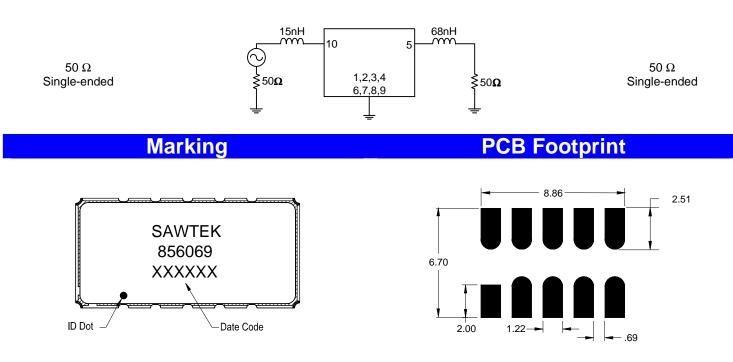


Typical Performance (at room temperature)





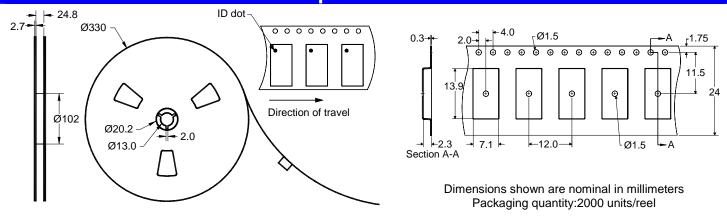
Matching Schematics



The date code consists of: JJJ = Julian day, Y = last digit of year, M = manufacturing site code

This footprint represents a recommendation only Dimensions shown are nominal in millimeters

Tape and Reel





Maximum Ratings							
Parameter	Symbol	Minimum	Maximum	Unit			
Operating Temperature Range	Т	-30	+85	°C			
Storage Temperature Range	T _{stg}	-40	+85	°C			

Important Notes

Warnings

- Electrostatic Sensitive Device (ESD)
- Avoid ultrasonic exposure

RoHS Compliance

• This product complies with EU directive 2002/95/EC (RoHS) (Pb)

Solderability

- Compatible with JESD22-B102, Pb-free process, 260C peak reflow temperature (see soldering profile)
 - **Links to Additional Technical Information**

PCB Layout Tips

Qualification Flowchart

Soldering Profile

S-Parameters

RoHS Information

Other Technical Information

TriQuint's liability is limited only to the Surface Acoustic Wave (SAW) component(s) described in this data sheet. TriQuint does not accept any liability for applications, processes, circuits or assemblies, which are implemented using any TriQuint component described in this data sheet.

Contact Information

TriQuint Construction SEMICONDUCTOR PO Box 609501 Orlando, FL 32860-9501 USA Phone: +1 (407) 886-8860 Fax: +1 (407) 886-7061 Email: <u>info-product@tqs.com</u> Web: www.triquint.com

Or contact one of our worldwide Network of <u>sales offices</u>, representatives or distributors

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